

PROBE OF UNDER SIDE OF COMPONENT THROUGH OPENING IN A PRINTED CIRCUIT BOARD

Abstract of the Disclosure

5 A test device includes an element having a surface for contacting a first plane, and a probe having a free end positioned in a second plane. The element of the test having the surface to contact the first plane includes features for contacting a ground plane. The length of the probe in the test device is greater than the length of the element having a surface for contacting the first plane. An electronic package
10 includes a printed circuit board having a primary side, and a secondary side. A component, having a main body, is attached to the primary side of the printed circuit board. A pad is attached to the main body of the component. The printed circuit board has an opening therein positioned near the pad. The probe passes through the opening in the printed circuit board to contact the pad from the secondary side of the
15 printed circuit board. A method for testing a device under test includes contacting a first pad on the device under test located in a first plane, and contacting a second pad on the device under test in a second plane substantially simultaneously as contacting the first pad.